

Title (en)
METHOD FOR PRODUCING AN ELECTRONIC UNIT AND ELECTRONIC UNIT

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN BAUGRUPPE UND ELEKTRONISCHE BAUGRUPPE

Title (fr)
PROCÉDÉ DE FABRICATION D'UN MODULE ÉLECTRONIQUE, AINSI QUE MODULE ÉLECTRONIQUE

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Application
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Abstract (en)
[origin: WO2011082778A2] The invention relates to a method for producing an electronic unit, wherein at least one electronic component is at least partially embedded in an insulating material, comprising the following steps: providing a film assembly with at least one conductive layer and a carrier layer, or with only a conductive layer, structuring the conductive layer such that openings in form of blind holes or through holes for receiving bumps are produced, which are connected to the contact surfaces of the at least one electronic component, applying an adhesive layer to the conductive layer provided with openings, placing the at least one component on the film assembly, or in the conductive layer, such that the bumps engage with the openings of the conductive layer, partially embedding the at least one component from the side opposite of the bumps (3) into a dielectric layer, removing the carrier layer of the film assembly, or a part of the conductive layer, such that the surface of the bumps is exposed, depositing a metallization layer on the side of the remaining conductive layer having the exposed bumps, and structuring the metallization layer and the conductive layer so as to produce conductor tracks that overlap with the bumps. The invention further relates to an electronic unit produced by such a method.

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